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Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-VQFP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rd2-lie

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



5. Pin Configuration



*NIC: No Internal Connection



	Pin Number		T							
Mnemonic	DIL	LCC	VQFP 1.4	Туре	Name And Function					
V _{SS}	20	22	16	Ι	Ground: 0V reference					
Vss1		1	39	Ι	Optional Ground: Contact the Sales Office for ground connection.					
V _{CC}	40	44	38	Ι	Power Supply: This is the power supply voltage for normal, idle and power-down operation					
P0.0-P0.7	39-32	43-36	37-30	I/O	Port 0 : Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.					
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:					
	1	2	40	I/O	T2 (P1.0): Timer/Counter 2 external count input/Clockout					
	2	3	41	I	T2EX (P1.1): Timer/Counter 2 Reload/Capture/Direction Control					
	3	4	42	Ι	ECI (P1.2): External Clock for the PCA					
	4	5	43	I/O	CEX0 (P1.3): Capture/Compare External I/O for PCA module 0					
	5	6	44	I/O	CEX1 (P1.4): Capture/Compare External I/O for PCA module 1					
	6	7	45	I/O	CEX0 (P1.5): Capture/Compare External I/O for PCA module 2					
	7	8	46	I/O	CEX0 (P1.6): Capture/Compare External I/O for PCA module 3					
	8	9	47	I/O	CEX0 (P1.7): Capture/Compare External I/O for PCA module 4					
P2.0-P2.7	21-28	24-31	18-25	I/O	Port 2 : Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 SFR. Some Port 2 pins (P2.0 to P2.5) receive the high order address bits during EPROM programming and verification:					
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Some Port 3 pins (P3.4 to P3.5) receive the high order address bits during EPROM programming and verification. Port 3 also serves the special features of the 80C51 family, as listed below.					
	10	11	5	I	RXD (P3.0): Serial input port					
	11	13	7	0	TXD (P3.1): Serial output port					
	12	14	8	I	INTO (P3.2): External interrupt 0					
	13	15	9	I	INT1 (P3.3): External interrupt 1					
	14	16	10	I	T0 (P3.4): Timer 0 external input					
	15	17	11	I	T1 (P3.5): Timer 1 external input					
	16	18	12	0	WR (P3.6): External data memory write strobe					
	17	19	13	0	RD (P3.7): External data memory read strobe					



Reset	9	10	4	Ι	Reset: A high on this pin for two machine cycles while the oscillator is running,
					resets the device. An internal diffused resistor to $V_{\mbox{\scriptsize SS}}$ permits a power-on reset
					using only an external capacitor to V_{CC} . If the hardware watchdog reaches its
					time-out, the reset pin becomes an output during the time the internal reset is
					activated.



6. TS80C51Rx2 Enhanced Features

In comparison to the original 80C52, the TS80C51Rx2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The extended RAM.
- The Programmable Counter Array (PCA).
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

6.1. X2 Feature

The TS80C51Rx2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

6.1.1. Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2. shows the mode switching waveforms.



Figure 1. Clock Generation Diagram



6.3. Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of ramdom access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 5.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. For example: MOV 0A0H, # data ,accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. For example: MOV @R0, # data where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With <u>EXTRAM = 0</u>, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to XRAM will not affect ports P0, P2, P3.6 (\overline{WR}) and P3.7 (\overline{RD}). For example, with EXTRAM = 0, MOVX @R0, # data where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure . For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With <u>EXTRAM = 1</u>, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 (WR) and P3.7 (RD).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.



• The ECF bit which when set causes an interrupt and the PCA overflow flag CF (in the CCON SFR) to be set when the PCA timer overflows.



6.5.4. Pulse Width Modulator Mode

All of the PCA modules can be used as PWM outputs. Figure 12 shows the PWM function. The frequency of the output depends on the source for the PCA timer. All of the modules will have the same frequency of output because they all share the PCA timer. The duty cycle of each module is independently variable using the module's capture register CCAPLn. When the value of the PCA CL SFR is less than the value in the module's CCAPLn SFR the output will be low, when it is equal to or greater than the output will be high. When CL overflows from FF to 00, CCAPLn is reloaded with the value in CCAPHn. This allows updating the PWM without glitches. The PWM and ECOM bits in the module's CCAPMn register must be set to enable the PWM mode.



Figure 12. PCA PWM Mode

6.5.5. PCA Watchdog Timer

An on-board watchdog timer is available with the PCA to improve the reliability of the system without increasing chip count. Watchdog timers are useful for systems that are susceptible to noise, power glitches, or electrostatic discharge. Module 4 is the only PCA module that can be programmed as a watchdog. However, this module can still be used for other modes if the watchdog is not needed. Figure 10 shows a diagram of how the watchdog works. The user pre-loads a 16-bit value in the compare registers. Just like the other compare modes, this 16-bit value is compared to the PCA timer value. If a match is allowed to occur, an internal reset will be generated. This will not cause the RST pin to be driven high.

In order to hold off the reset, the user has three options:

- 1. periodically change the compare value so it will never match the PCA timer,
- 2. periodically change the PCA timer value so it will never match the compare values, or
- 3. disable the watchdog by clearing the WDTE bit before a match occurs and then re-enable it.

The first two options are more reliable because the watchdog timer is never disabled as in option #3. If the program counter ever goes astray, a match will eventually occur and cause an internal reset. The second option is also not recommended if other PCA modules are being used. Remember, the PCA timer is the time base for all modules; changing the time base for other modules would not be a good idea. Thus, in most applications the first solution is the best option.

This watchdog timer won't generate a reset out on the reset pin.



6.6. TS80C51Rx2 Serial I/O Port

The serial I/O port in the TS80C51Rx2 is compatible with the serial I/O port in the 80C52. It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous

Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

6.6.1. Framing Error Detection

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 13).



Figure 13. Framing Error Block Diagram

When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 16.) bit is set.



6.6.5. Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b Not bit addressable

SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b Not bit addressable



Table 18. Priority Level Bit Values

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 19. IE Register

IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	EC	ET2	ES	ET1	EX1	ЕТО	EX0

Bit Number	Bit Mnemonic	Description
7	EA	Enable All interrupt bit Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.
6	EC	PCA interrupt enable bit Clear to disable . Set to enable.
5	ET2	Timer 2 overflow interrupt Enable bit Clear to disable timer 2 overflow interrupt. Set to enable timer 2 overflow interrupt.
4	ES	Serial port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.
3	ET1	Timer 1 overflow interrupt Enable bit Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.
2	EX1	External interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.
1	ET0	Timer 0 overflow interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.
0	EX0	External interrupt 0 Enable bit Clear to disable external interrupt 0. Set to enable external interrupt 0.

Reset Value = 0000 0000b Bit addressable



Table 21. IPH Register

IPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0				
-	РРСН	РТ2Н	PSH	PT1H	PX1H	РТОН	РХОН				
Bit Number	Bit Mnemonic		Description								
7	-	Reserved The value read f	Reserved The value read from this bit is indeterminate. Do not set this bit.								
6	РРСН	PCA interrupt prio <u>PPCH</u> 0 1 1	rity bit high. <u>PPC</u> Prio 0 1 0 1	<u>rity Level</u> Lowest Highest							
5	РТ2Н	Timer 2 overflow in <u>PT2H</u> 0 1 1 1	terrupt Priority E <u>PT2</u> 0 1 0 1	ligh bit <u>Priority Level</u> Lowest Highest							
4	PSH	Serial port Priority PSH 0 1 1	High bit <u>PS</u> 0 1 0 1	<u>Priority Level</u> Lowest Highest							
3	PT1H	Timer 1 overflow in <u>PT1H</u> 0 0 1 1 1	terrupt Priority E <u>PT1</u> 0 1 0 1	ligh bit <u>Priority Level</u> Lowest Highest							
2	PX1H	External interrupt 1 <u>PX1H</u> 0 0 1 1 1	l Priority High bi <u>PX1</u> 0 1 0 1 1	t <u>Priority Level</u> Lowest Highest							
1	РТОН	Timer 0 overflow in <u>PT0H</u> 0 1 1	terrupt Priority E <u>PTO</u> 0 1 0 1 1	ligh bit <u>Priority Level</u> Lowest Highest							
0	РХ0Н	External interrupt (<u>PX0H</u> 0 0 1 1 1) Priority High bi <u>PX0</u> 0 1 0 1	t <u>Priority Level</u> Lowest Highest							

Reset Value = X000 0000b Not bit addressable



Table 24. WDTPRG Register

7	6		5	4	3	2	1	0					
T4	Т3		T2	T1	TO	S2	S1	S0					
Bit Number	Bit Mnemonic		Description										
7	T4												
6	T3		Reserved Do not try to set or clear this bit.										
5	T2	Reserve Do 1											
4	T1												
3	TO												
2	S2	WDT Ti	ime-out sele	et bit 2									
1	S1	WDT Ti	ime-out sele	et bit 1									
0	SO	WDT Ti	ime-out sele	et bit 0									
			<u>S1</u> 0 1 1 0 0 1 1	$\begin{array}{c cccc} \underline{S0} & \underline{Selecter} \\ 0 & (2^{14} - 1) \\ 1 & (2^{15} - 1) \\ 0 & (2^{16} - 1) \\ 1 & (2^{17} - 1) \\ 0 & (2^{18} - 1) \\ 1 & (2^{19} - 1) \\ 0 & (2^{20} - 1) \\ 1 & (2^{21} - 1) \end{array}$	1 Time-out 9 machine cycles, 10 9 machine cycles, 32 9 machine cycles, 63 9 machine cycles, 12 9 machine cycles, 20 9 machine cycles, 55 9 machine cycles, 1 9 machine cycles, 1 9 machine cycles, 2	5.3 ms @ 12 MHz 2.7 ms @ 12 MHz 5.5 ms @ 12 MHz 31 ms @ 12 MHz 62 ms @ 12 MHz 42 ms @ 12 MHz 05 s @ 12 MHz 09 s @ 12 MHz							

Reset value XXXX X000

6.10.2. WDT during Power Down and Idle

In Power Down mode the oscillator stops, which means the WDT also stops. While in Power Down mode the user does not need to service the WDT. There are 2 methods of exiting Power Down mode: by a hardware reset or via a level activated external interrupt which is enabled prior to entering Power Down mode. When Power Down is exited with hardware reset, servicing the WDT should occur as it normally should whenever the TS80C51Rx2 is reset. Exiting Power Down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service routine.

To ensure that the WDT does not overflow within a few states of exiting of powerdown, it is best to reset the WDT just before entering powerdown.

In the Idle mode, the oscillator continues to run. To prevent the WDT from resetting the TS80C51Rx2 while in Idle mode, the user should always set up a timer that will periodically exit Idle, service the WDT, and re-enter Idle mode.

WDTPRG Address (0A7h)



6.12. Power-Off Flag

The power-off flag allows the user to distinguish between a "cold start" reset and a "warm start" reset.

A cold start reset is the one induced by V_{CC} switch-on. A warm start reset occurs while V_{CC} is still applied to the device and could be generated for example by an exit from power-down.

The power-off flag (POF) is located in PCON register (See Table 26.). POF is set by hardware when V_{CC} rises from 0 to its nominal voltage. The POF can be set or cleared by software allowing the user to determine the type of reset.

The POF value is only relevant with a Vcc range from 4.5V to 5.5V. For lower Vcc value, reading POF bit will return indeterminate value.

Table 26. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0				
SMOD1	SMOD	-	POF	GF1	GF0	PD	IDL				
Bit Number	Bit Mnemonic		Description								
7	SMOD1	Serial port Mode bit Set to select dou	Serial port Mode bit 1 Set to select double baud rate in mode 1, 2 or 3.								
6	SMOD0	Serial port Mode bit Clear to select SI Set to to select F	clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.								
5	-	Reserved The value read fr	Reserved The value read from this bit is indeterminate. Do not set this bit.								
4	POF	Power-Off Flag Clear to recogniz Set by hardware	Power-Off Flag Clear to recognize next reset type. Set by hardware when V _{CC} rises from 0 to its nominal voltage. Can also be set by software.								
3	GF1	General purpose Fla Cleared by user f Set by user for g	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.								
2	GF0	General purpose Fla Cleared by user f Set by user for g	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.								
1	PD	Power-Down mode I Cleared by hardw Set to enter powe	bit ware when reset oc wr-down mode.	curs.							
0	IDL	Idle mode bit Clear by hardwar Set to enter idle r	e when interrupt on ode.	or reset occurs.							

Reset Value = 00X1 0000b Not bit addressable



7. TS83C51RB2/RC2/RD2 ROM

7.1. ROM Structure

The TS83C51RB2/RC2/RD2 ROM memory is divided in three different arrays:

•	the code array:	es.
•	the encryption array:	s.
•	the signature array:	es.

7.2. ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

7.2.1. 7.2.1. Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

7.2.2. Program Lock Bits

The lock bits when programmed according to Table 28. will provide different level of protection for the on-chip code and data.

	Program	Lock Bits					
Security level	LB1	LB2	LB3	Protection description			
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.			
2	Р	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset.			
3	U	Р	U	Same as level 1+ Verify disable. This security level is only available for 51RDX2 devices.			

Table	28.	Program	Lock	bits
-------	-----	---------	------	------

U: unprogrammed

P: programmed

7.2.3. Signature bytes

The TS83C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.

7.2.4. Verify Algorithm

Refer to 8.3.4.





* See Table 31. for proper value on these inputs

Figure 18. Set-Up Modes Configuration

8.3.3. Programming Algorithm

The Improved Quick Pulse algorithm is based on the Quick Pulse algorithm and decreases the number of pulses applied during byte programming from 25 to 1.

To program the TS87C51RB2/RC2/RD2 the following sequence must be exercised:

- Step 1: Activate the combination of control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Input the appropriate data on the data lines.
- Step 4: Raise \overline{EA}/VPP from VCC to VPP (typical 12.75V).
- Step 5: Pulse ALE/PROG once.
- Step 6: Lower \overline{EA}/VPP from VPP to VCC

Repeat step 2 through 6 changing the address and data for the entire array or until the end of the object file is reached (See Figure 19.).

8.3.4. Verify algorithm

Code array verify must be done after each byte or block of bytes is programmed. In either case, a complete verify of the programmed array will ensure reliable programming of the TS87C51RB2/RC2/RD2.

P 2.7 is used to enable data output.

To verify the TS87C51RB2/RC2/RD2 code the following sequence must be exercised:

- Step 1: Activate the combination of program and control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Read data on the data lines.

Repeat step 2 through 3 changing the address for the entire array verification (See Figure 19.)

The encryption array cannot be directly verified. Verification of the encryption array is done by observing that the code array is well encrypted.





Figure 19. Programming and Verification Signal's Waveform

8.4. EPROM Erasure (Windowed Packages Only)

Erasing the EPROM erases the code array, the encryption array and the lock bits returning the parts to full functionality.

Erasure leaves all the EPROM cells in a 1's state (FF).

8.4.1. Erasure Characteristics

The recommended erasure procedure is exposure to ultraviolet light (at 2537 Å) to an integrated dose at least 15 W-sec/cm². Exposing the EPROM to an ultraviolet lamp of 12,000 μ W/cm² rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.



10.3. DC Parameters for Standard Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz. TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 32. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	$0.2 V_{CC} + 0.9$		V _{CC} + 0.5	v	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A^{(4)}$ $I_{OL} = 1.6 \ m A^{(4)}$ $I_{OL} = 3.5 \ m A^{(4)}$
V _{OL1}	Output Low Voltage, port 0 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 200 \ \mu A^{(4)}$ $I_{OL} = 3.2 \ m A^{(4)}$ $I_{OL} = 7.0 \ m A^{(4)}$
V _{OL2}	Output Low Voltage, ALE, PSEN			0.3 0.45 1.0	V V V	$\begin{split} I_{OL} &= 100 \; \mu A^{(4)} \\ I_{OL} &= 1.6 \; m A^{(4)} \\ I_{OL} &= 3.5 \; m A^{(4)} \end{split}$
V _{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$\begin{split} I_{OH} &= -10 \; \mu A \\ I_{OH} &= -30 \; \mu A \\ I_{OH} &= -60 \; \mu A \\ V_{CC} &= 5 \; V \pm 10\% \end{split}$
V _{OH1}	Output High Voltage, port 0	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$I_{OH} = -200 \ \mu A$ $I_{OH} = -3.2 \ m A$ $I_{OH} = -7.0 \ m A$ $V_{CC} = 5 \ V \pm 10\%$
V _{OH2}	Output High Voltage, ALE, PSEN	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$I_{OH} = -100 \ \mu A$ $I_{OH} = -1.6 \ m A$ $I_{OH} = -3.5 \ m A$ $V_{CC} = 5 \ V \pm 10\%$
R _{RST}	RST Pulldown Resistor	50	90 ⁽⁵⁾	200	kΩ	
I _{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	μΑ	Vin = 0.45 V
I _{LI}	Input Leakage Current			±10	μΑ	0.45 V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	μA	Vin = 2.0 V
C _{IO}	Capacitance of I/O Buffer			10	pF	$Fc = 1 MHz$ $TA = 25^{\circ}C$
I _{PD}	Power Down Current		20 (5)	50	μΑ	$2.0 \ V < V_{CC} < 5.5 \ V^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	$V_{CC} = 5.5 V^{(1)}$



10.5.2. External Program Memory Characteristics

Table 36. Symbol Description	Table 3	36.	Symbol	Description
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Symbol	Parameter
Т	Oscillator clock period
T _{LHLL}	ALE pulse width
T _{AVLL}	Address Valid to ALE
T _{LLAX}	Address Hold After ALE
T _{LLIV}	ALE to Valid Instruction In
T _{LLPL}	ALE to PSEN
T _{PLPH}	PSEN Pulse Width
T _{PLIV}	PSEN to Valid Instruction In
T _{PXIX}	Input Instruction Hold After PSEN
T _{PXIZ}	Input Instruction FloatAfter PSEN
T _{PXAV}	PSEN to Address Valid
T _{AVIV}	Address to Valid Instruction In
T _{PLAZ}	PSEN Low to Address Float

Table 37. AC Parameters for Fix Clock

Speed	-1 40 N	М ЛНz	X2 r 30 M 60 MH	V node MHz z equiv.	standar 40 N	V rd mode MHz	X2 r 20 N 40 MH	L node MHz z equiv.	standar 30 N	L [.] d mode ⁄IHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Т	25		33		25		50		33		ns
T _{LHLL}	40		25		42		35		52		ns
T _{AVLL}	10		4		12		5		13		ns
T _{LLAX}	10		4		12		5		13		ns
T _{LLIV}		70		45		78		65		98	ns
T _{LLPL}	15		9		17		10		18		ns
T _{PLPH}	55		35		60		50		75		ns
T _{PLIV}		35		25		50		30		55	ns
T _{PXIX}	0		0		0		0		0		ns
T _{PXIZ}		18		12		20		10		18	ns
T _{AVIV}		85		53		95		80		122	ns
T _{PLAZ}		10		10		10		10		10	ns



10.5.9. EPROM Programming and Verification Characteristics

TA = 21°C to 27°C; $V_{SS} = 0V$; $V_{CC} = 5V \pm 10\%$ while programming. V_{CC} = operating range while verifying

Symbol	Parameter	Min	Max	Units
V _{PP}	Programming Supply Voltage	12.5	13	V
I _{PP}	Programming Supply Current		75	mA
1/T _{CLCL}	Oscillator Frquency	4	6	MHz
T _{AVGL}	Address Setup to PROG Low	48 T _{CLCL}		
T _{GHAX}	Adress Hold after PROG	48 T _{CLCL}		
T _{DVGL}	Data Setup to PROG Low	48 T _{CLCL}		
T _{GHDX}	Data Hold after PROG	48 T _{CLCL}		
T _{EHSH}	(Enable) High to V _{PP}	48 T _{CLCL}		
T _{SHGL}	V _{PP} Setup to PROG Low	10		μs
T _{GHSL}	V _{PP} Hold after PROG	10		μs
T _{GLGH}	PROG Width	90	110	μs
T _{AVQV}	Address to Valid Data		48 T _{CLCL}	
T _{ELQV}	ENABLE Low to Data Valid		48 T _{CLCL}	
T _{EHQZ}	Data Float after ENABLE	0	48 T _{CLCL}	

Table 45. EPROM Programming Parameters

10.5.10. EPROM Programming and Verification Waveforms



* 8KB: up to P2.4, 16KB: up to P2.5, 32KB: up to P3.4, 64KB: up to P3.5

Figure 29. EPROM Programming and Verification Waveforms



11. Ordering Information



(*) Check with Atmel Wireless & Microcontrollers Sales Office for availability. Ceramic packages (J, K, N) are available for proto typing, not for volume production. Ceramic packages are available for OTP only.

Table	47.	Maximum	Clock	Frequency
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Code	-M	-V	-L	Unit
Standard Mode, oscillator frequency	40	40	30	MHz
Standard Mode, internal frequency	40	40	30	
X2 Mode, oscillator frequency	20	30	20	MHz
X2 Mode, internal equivalent frequency	40	60	40	